



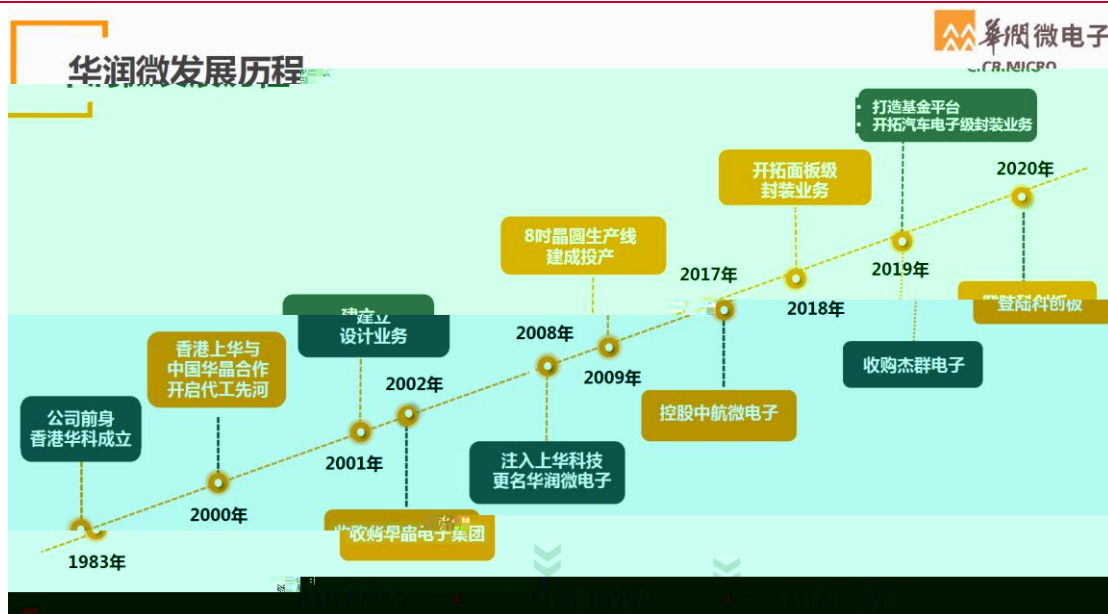
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1.

IDM

1.1.

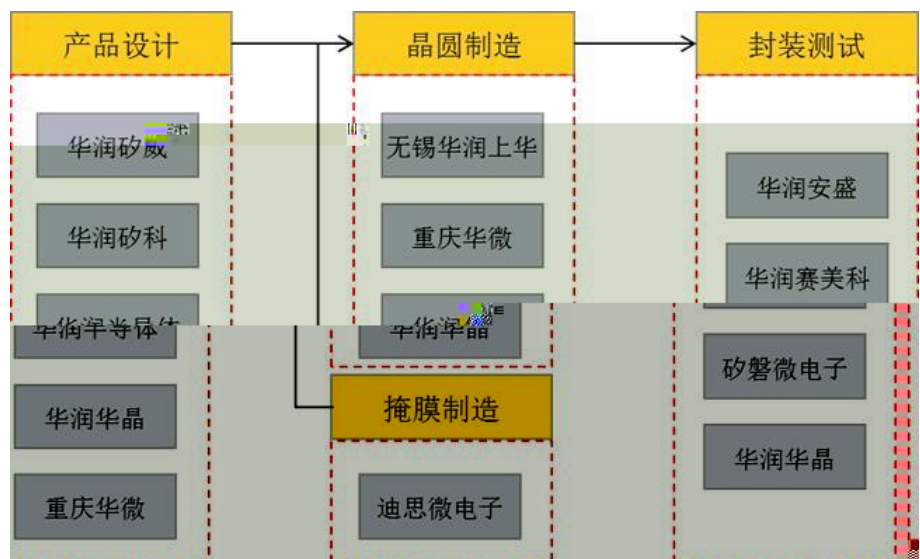
1



4

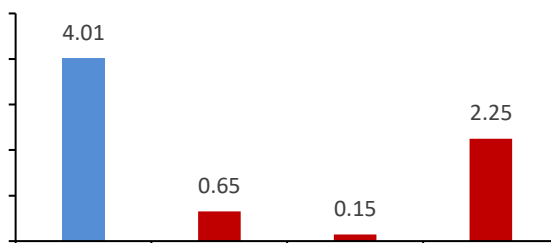
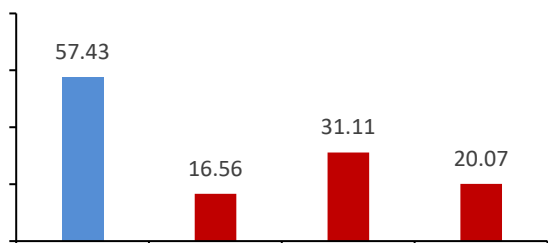
1.2.

5



6

8



1.3.

11



BCD

MEMS MEMS

CMOS

MEMS

13

晶圆制造

提供优质性价比的6+8代工服务
中国排名前三本土晶圆制造企业




掩模制造

中国生产光掩模产品的主要有四家，2018年华润信掩模市占率排名第一
中国四大本土掩模制造企业之一

封装测试

公司具有完备的半导体封装生产工艺及板级、数字、混合信号等多类导体测试生产工艺



提供具有竞争力的特色晶圆代工平台

- 大陆首家推出超高压1.0/0.8μm700V BCD工艺平台并率先量产
- 国内首条高压SOI工艺平台规模化生产线
- 国内领先的MEMS代工生产线
- 提供国内独有的200V/600V HVIC代工平台，用于电机驱动

多样化的封装形式

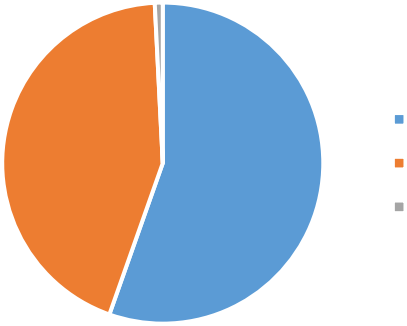
中测-封装-测试-烧带一站式服务

高精稳定的三星测试

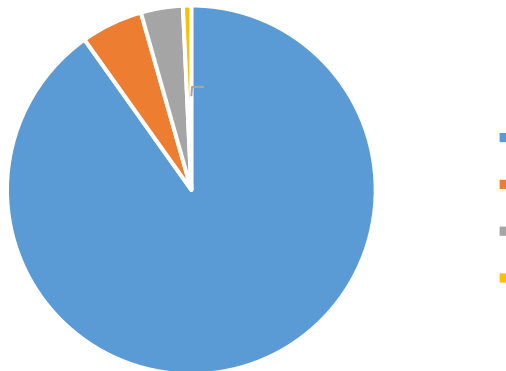
先进封装技术：倒装、Flip chip技术

封装形式：QFN, FC-QFN, FC-DFP, TQFP, BGA, SOP, TSOP, DIP, LQFP, SSOP, SOIC, POP, DFN, DFN-DFP, SOI, POPs, DM-DCDFP, SOI POPs

15

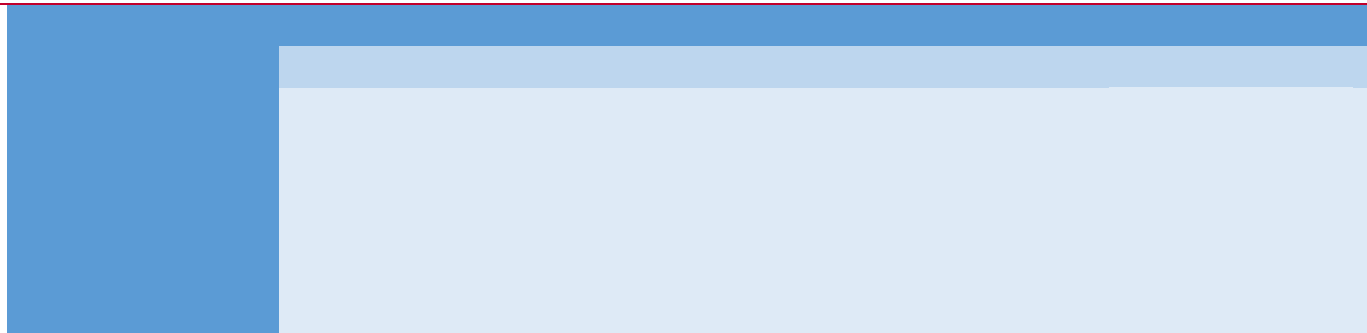


16



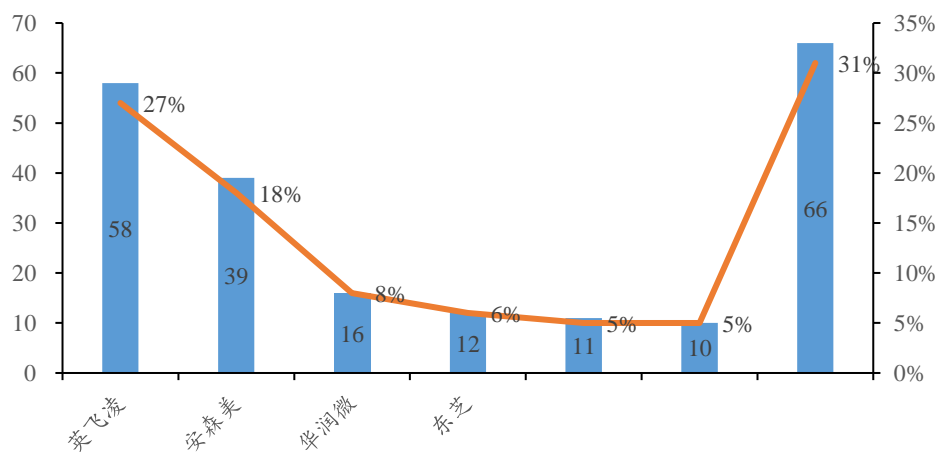
MOSFET
IDM

17



MOSFET

18



IGBT

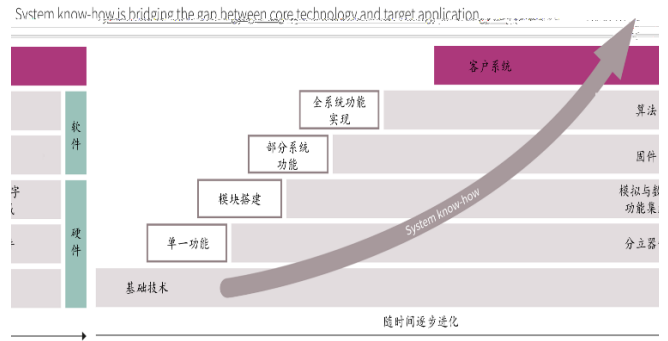
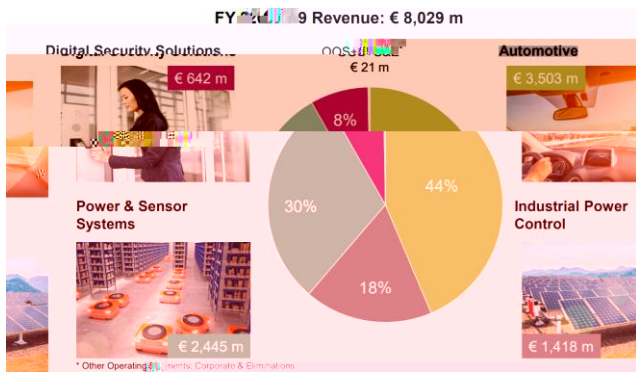
Trench-FS

600V-6500VIGBT

IC BCD

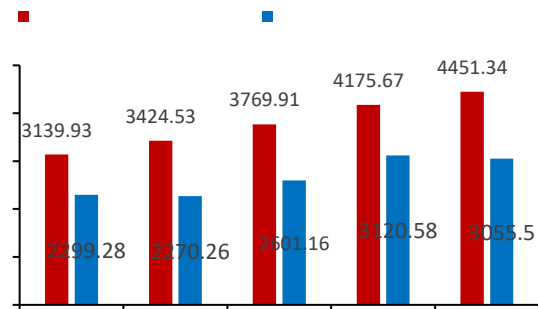
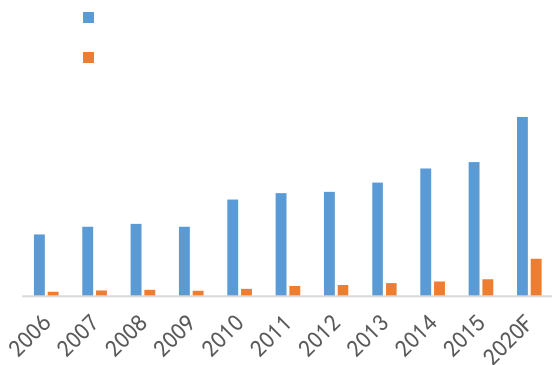
+

19



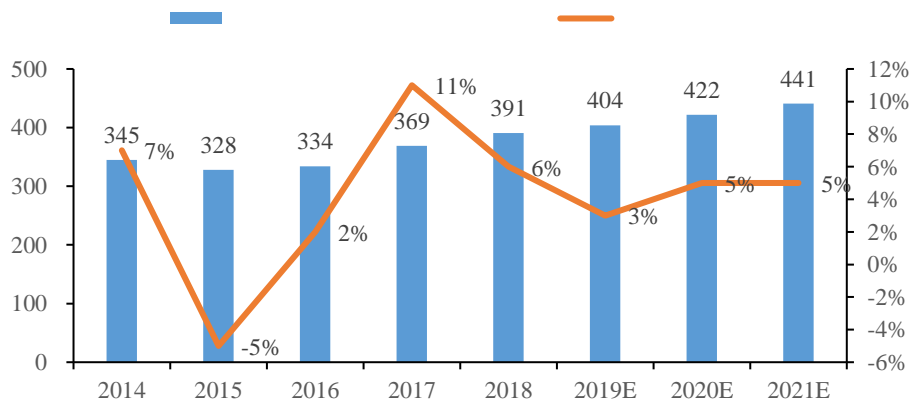
2. +

2.1.

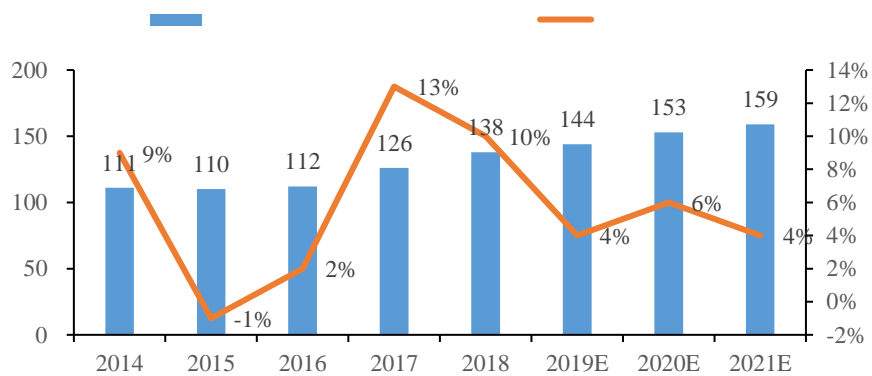


2.2.

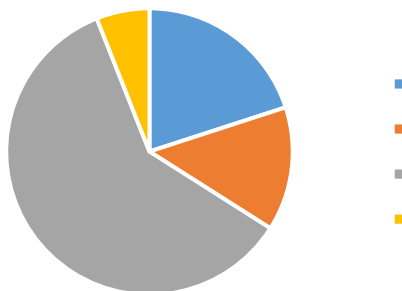
27



28

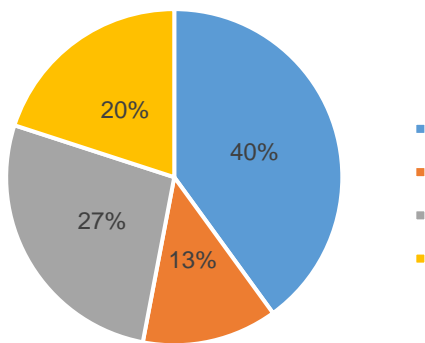


29

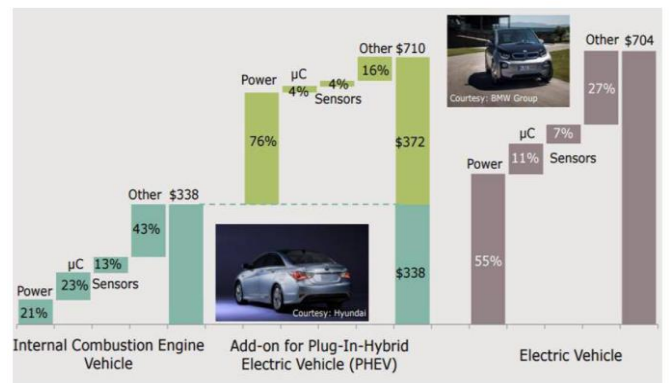


ASP

30

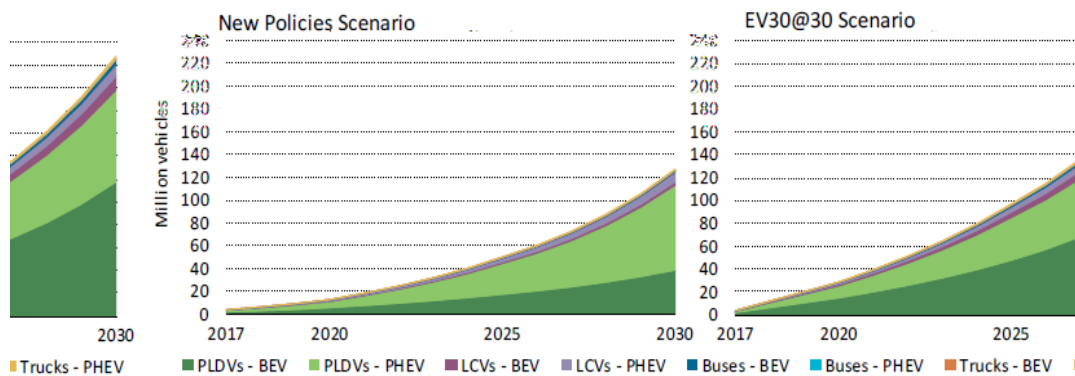


31

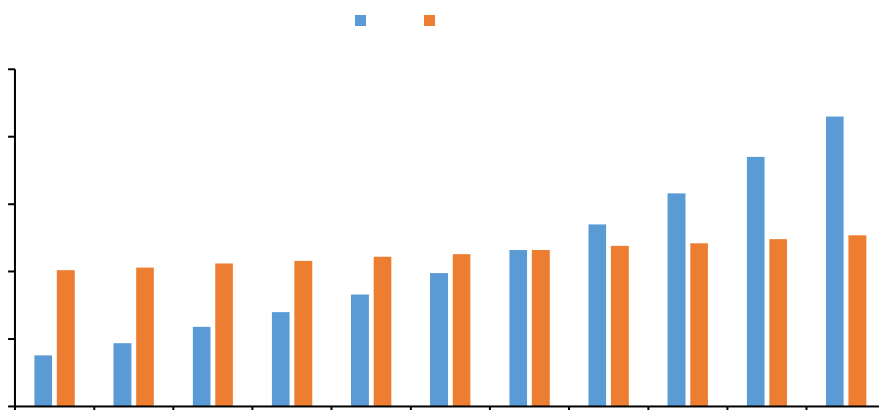


50

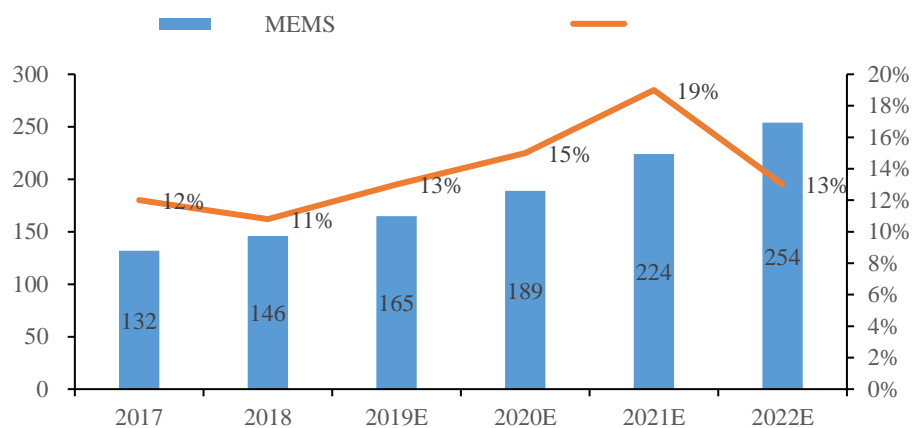
32



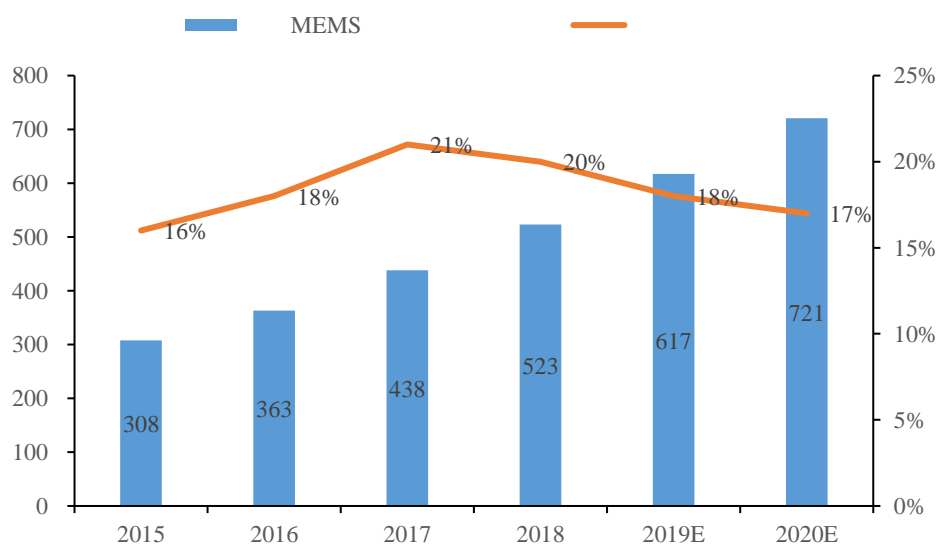
33



34 MEMS



35 MEMS



MEMS

IDM

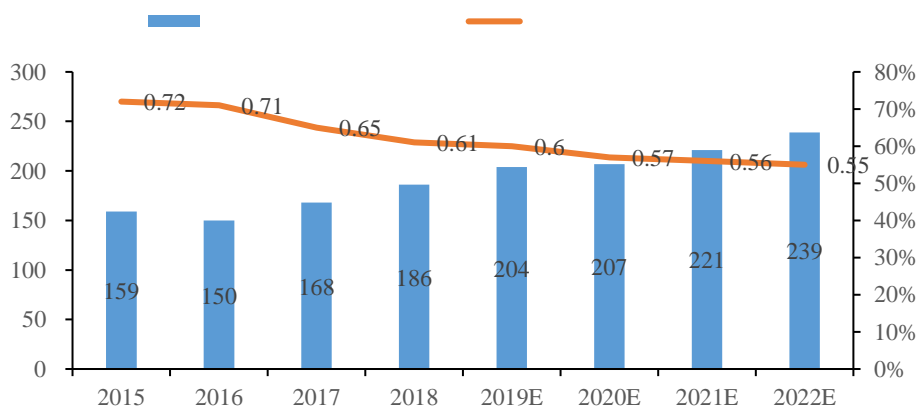
3 MCU

MCU

MCU

240

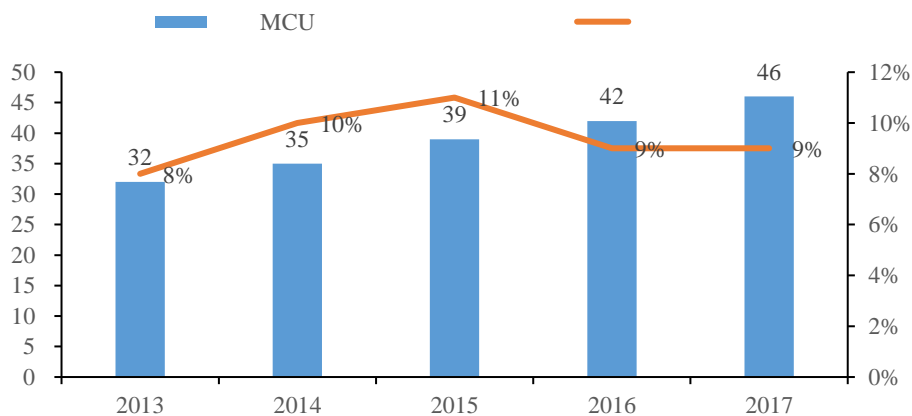
36



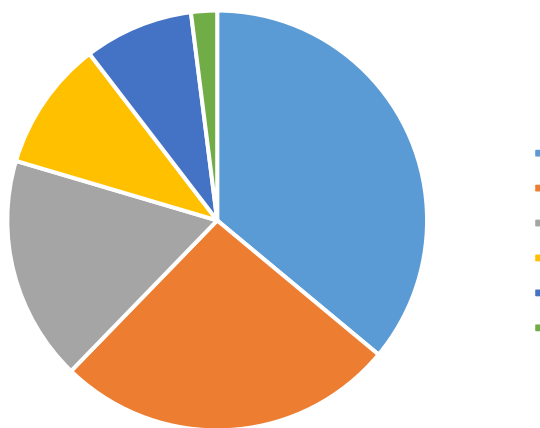
MCU

40

37



30%



MCU

2.3.

39

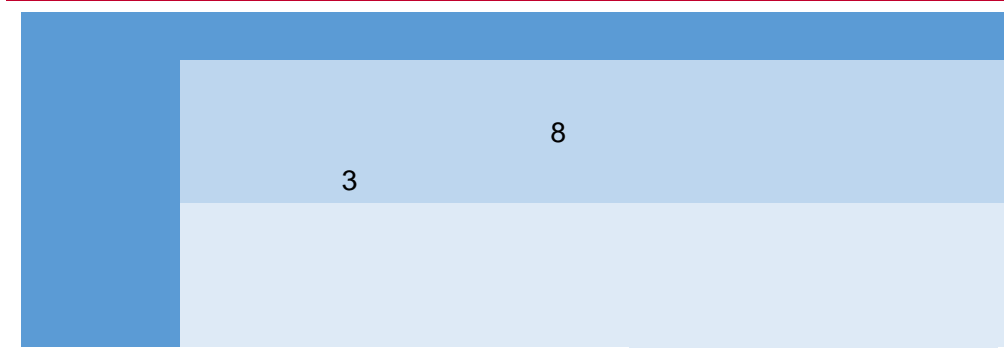
39			

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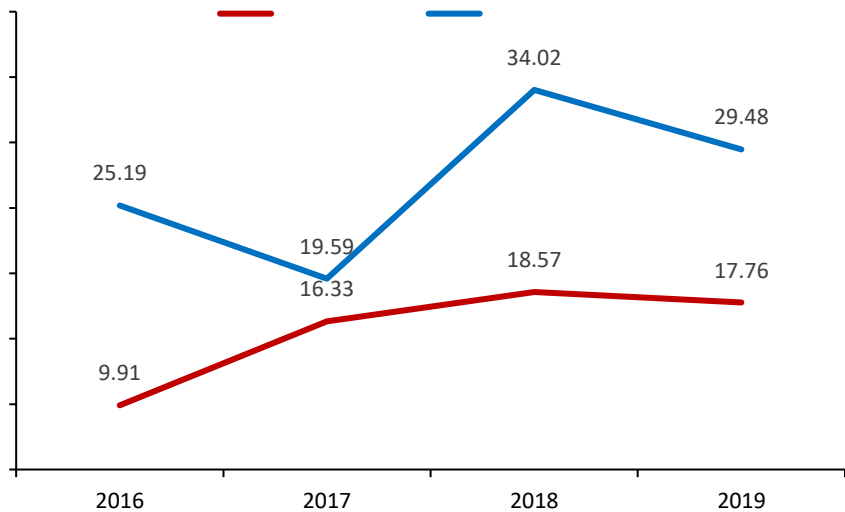
40



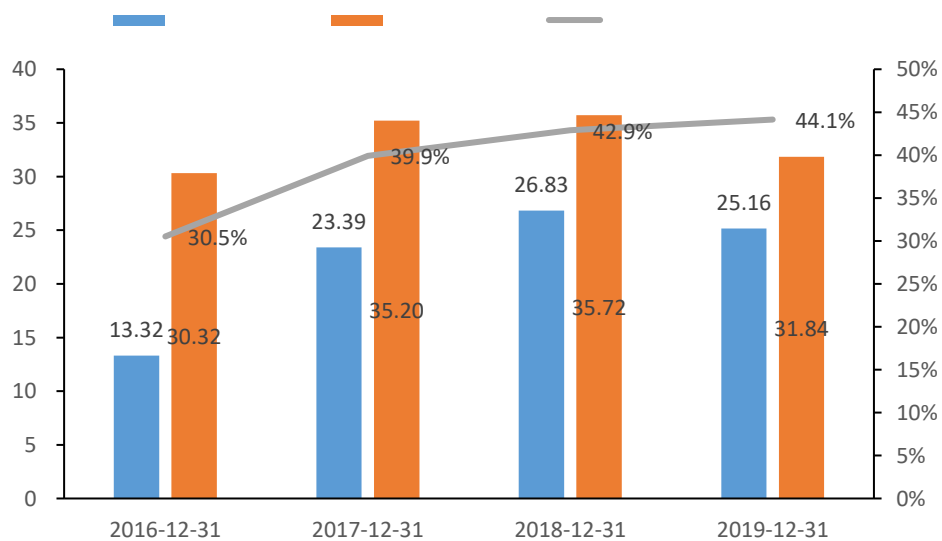
3.

3.1.

41

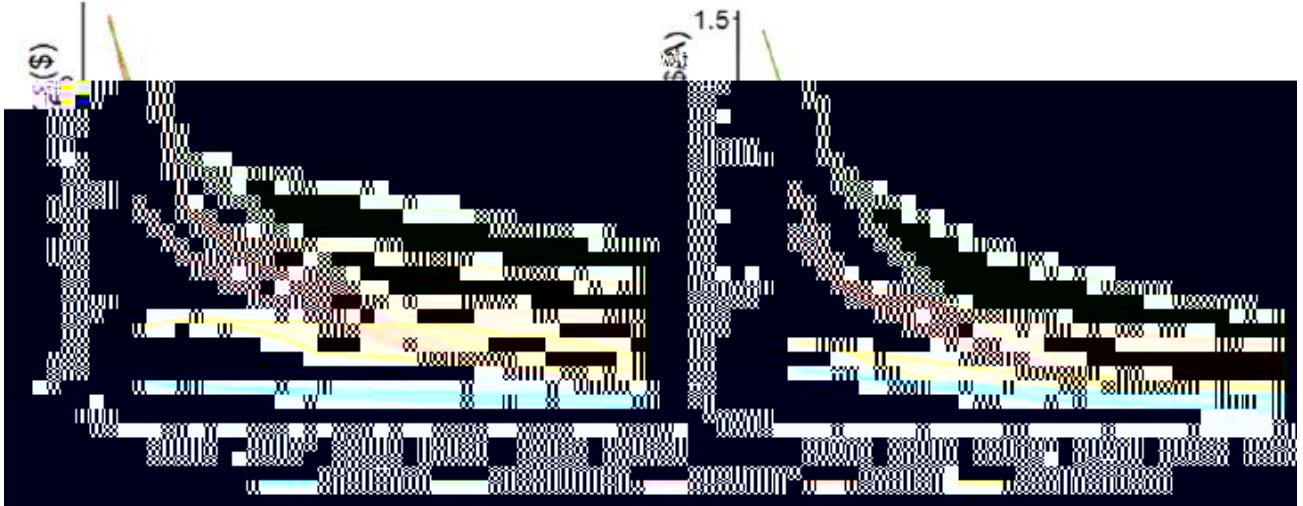


42



3.2.

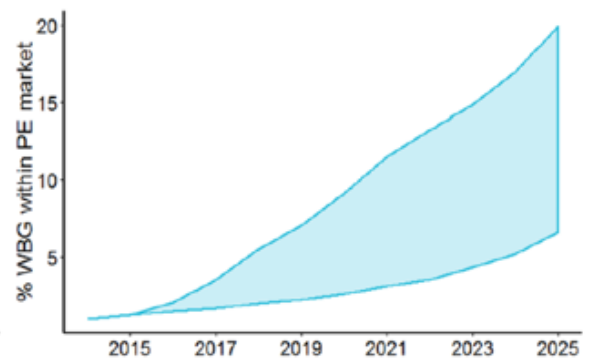
44 SiC



45 SiC



46



4.
